

D.VERKEST







CMOS SCALING: THE BAD

Switching heat/cm² ~ $(V_{DD}/\lambda)^3$ V_{DD} Leakage Power ~ exp(-mV_T/kT) $\rightarrow V_T$ Clock $F_{cl} \sim I_{on}/V_{DD} \sim \mu (V_{DD} - V_T)^{0.5}/\lambda \rightarrow$ Clash

Device variability $\sigma V_T \sim I/\lambda \rightarrow \sigma F_{cl}$

Interconnect RC delay

CMOS SCALING: THE GOOD

- "Zero" static power: symmetric n and p FET
- Simple (planar) layout strategy (litho compatible)
- Symmetric $I/V \rightarrow$ bidirectional switch
- Gain: signal restoration, noise margin, RF and analog
- ► W/L sizing → Fanout I ... 10⁶
- Connectable by 10+ wiring layers
- Low manufacturing cost: < I n\$/transistor</p>
- Design technology and IP libraries
- Versatile: logic, storage, interconnect, I/O, analog, ...

→ complete System-on-Chip

Beyond CMOS device inventor

The CMOS designer

Source: W. Joyner, IBM

Beyond CMOS device inventor

Hey, here's a great new device ...

- It's really cool! It looks useful!
- We actually made one! It worked!

The CMOS designer



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- ... but I can't do design with them
 - I don't understand them.
 - You can't characterize them, model them, simulate them, make them in volume,

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SYSTEMABILITY

The ability to economically design and manufacture reliable systems from the interaction of devices fabricated in a given technology.

SYSTEM = COMPUTATION, STORAGE, INTERCONNECT, I/O, Every Contender

- Must add value to one or more of the 4 system functions and be compatible with the others
- All-in throughput/Watt and/or transactions/Joule must beat CMOS at time of manufacturing at equivalent or lower cost
- System level manufacturability, reliability, testability must beat ultimate CMOS solutions
- Room temperature operation is mandatory
- Device variability must be mitigated and modeled and cost efficient error resilient design solutions must be available
- Design methods and tools must be in place supporting design from device to system. Design tool development time is 3x technology development time.

PDK

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IMEC INSITE PATHFINDING INITIATIVE LINKING PROCESSES, DEVICES, CIRCUITS, SYSTEMS











BEYOND

BESIDE In the spirit of

Thomas J.Watson "I think there is a world market for maybe five computers."

BE NOT

BE IN

BEYOND

BESIDEMolecular electronics (plastic/organic)

BE IN

BE NOT

BEYOND

BESIDE

- Molecular electronics (plastic/organic)
- MEMS (complementary/on-top-off)

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BEYONDQuantum Computing

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- Molecular electronics (plastic/organic)
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- Graphene

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BE NOT